L Number	Hits	Search Text	DB	Time stamp
1	417	438/689,690.ccls.	USPAT	2002/12/24 11:43
2	1330	438/691,692.ccls.	USPAT	2002/12/24 11:52
3	1034	438/693,694.ccls.	USPAT	2002/12/24 11:43
4	521	438/695,697.ccls.	USPAT	2002/12/24 11:44
5	1053	lee-young$.in. kim-tae$.in. kim-jin$.in. an-jung$.in. song-jong$.in.	USPAT	2002/12/24 11:46
6	333	lee-young$.in. kim-tae$.in. kim-jin$.in. an-jung$.in. song-jong$.in.	US-PGPUB	2002/12/24 11:47
7	892	lee-young$.in. kim-tae$.in. kim-jin$.in. an-jung$.in. song-jong$.in.	EPO; JPO; DERWENT; IBM_TDB	2002/12/24 11:47
8	31721	(planar$8 "cmp" "CMP" polish$3) and (substrate wafer) and (photoresist resist)	USPAT	2002/12/24 11:57
9	20079	((planar$8 "cmp" "CMP" polish$3) and (substrate wafer) and (photoresist resist)) and ((planar$8 "cmp" "CMP" polish$3) same (substrate wafer))	USPAT	2002/12/24 11:55
10	4461	(((planar$8 "cmp" "CMP" polish$3) and (substrate wafer) and (photoresist resist)) and ((planar$8 "cmp" "CMP" polish$3) same (substrate wafer))) and ((planar$8 "cmp" "CMP" polish$3) adj2 (substrate wafer))	USPAT	2002/12/24 12:00
11	3657	((((planar$8 "cmp" "CMP" polish$3) and (substrate wafer) and (photoresist resist)) and ((planar$8 "cmp" "CMP" polish$3) same (substrate wafer))) and ((planar$8 "cmp" "CMP" polish$3) adj2 (substrate wafer))) and (etch$3 same (layer film))	USPAT	2002/12/24 11:56
12	3514	(((((planar$8 "cmp" "CMP" polish$3) and (substrate wafer) and (photoresist resist)) and ((planar$8 "cmp" "CMP" polish$3) same (substrate wafer))) and ((planar$8 "cmp" "CMP" polish$3) adj2 (substrate wafer))) and (etch$3 same (layer film))) and ((photoresist resist) same (wafer film layer substrate))	USPAT	2002/12/24 12:01
13	1135	((((((planar$8 "cmp" "CMP" polish$3) and (substrate wafer) and (photoresist resist)) and ((planar$8 "cmp" "CMP" polish$3) same (substrate wafer))) and ((planar$8 "cmp" "CMP" polish$3) adj2 (substrate wafer))) and (etch$3 same (layer film))) and ((photoresist resist) same (wafer film layer substrate))) and ((planar$8 "cmp" "CMP" polish$3) adj2 (layer film))	USPAT	2002/12/24 12:01
14	6965	((planar$8 "cmp" "CMP" polish$3) adj2 (layer film))	EP ; JP ; DERWENT; IBM_TDB	2002/12/24 12:02

15	634	(((planar$8 "cmp" "CMP" polish$3) adj2 (layer film))) and ((photoresist resist) same (wafer film layer substrate))	EP ; JP ; DERWENT; IBM_TDB	2002/12/24 12:02
16	3021	((planar$8 "cmp" "CMP" polish$3) adj2 (layer film))	US-PGPUB	2002/12/24 12:02
17	1470	(((planar$8 "cmp" "CMP" polish$3) adj2 (layer film))) and ((photoresist resist) same (wafer film layer substrate))	US-PGPUB	2002/12/24 12:02